

WHAT IS CLAIMED IS:

1. A printed-wiring substrate comprising:
a molded insulating substrate serving as a support;
a conductor layer formed on the insulating substrate; and
a capacitor element embedded in the insulating substrate and
5 connected to the conductor layer, wherein
the printed-wiring substrate (is adapted for mounting an integrated-circuit element thereon connecting to the conductor layer, characterized in that
(the insulating substrate is molded by placing the capacitor element in a predetermined mold and charging resin into the mold.)
2. The printed-wiring substrate according to claim 1, wherein the insulating substrate includes a reinforcement member embedded in the insulating substrate.
3. The printed-wiring substrate according to claim 2, wherein the insulating substrate includes, as the reinforcement member, glass cloth embedded in the insulating substrate.
4. The printed-wiring substrate according to claim 2, wherein the insulating substrate includes, as the reinforcement member, a metal plate embedded in the insulating substrate.

5. The printed-wiring substrate according to claim 1, wherein the insulating substrate has through holes and through-hole conductors formed on wall surfaces of the through holes.

6. The printed-wiring substrate according to claim 1, wherein the capacitor element has terminals on each of upper and lower surfaces thereof; and the terminals on the upper surface are exposed from an upper surface of the insulating substrate, and the terminals on the lower surface are exposed
5 from a lower surface of the insulating substrate.

7. The printed-wiring substrate according to claim 6, comprising at least one insulating layer formed on each of the upper and lower surfaces of the insulating substrate and at least one conductor layer formed on the insulating layer, wherein the conductor layer is connected to the terminals of
5 the capacitor element or the through-hole conductors by vias formed in the insulating layer.

8. The printed-wiring substrate according to claim 1, wherein the capacitor element has roughened side surfaces to increase the adhesion strength between the capacitor element and resin charged into the mold.

9. A method for fabricating a printed-wiring substrate including an insulating substrate formed of resin and serving as a support, a conductor layer formed on the insulating substrate, and a capacitor element connected to the conductor layer, the method comprising:

5 placing the capacitor element in a mold and charging resin into the
mold to thereby mold the insulating substrate;

exposing terminals of the capacitor element to the outside of the
insulating substrate; and

10 forming a conductor layer on the insulating substrate such that the
conductor layer is connected to the terminals of the capacitor element exposed
to the outside of the insulating substrate.

10. The method for fabricating a printed-wiring substrate according
to claim 9, wherein said charging comprises a plurality of charging operations,
and between subsequent charging operations, disposing a sheet of glass cloth
on a resin layer formed within the mold to form layers of the resin and the
5 layer of glass cloth alternately stacked in the thickness direction.

11. The method for fabricating a printed-wiring substrate according
to claim 9, wherein said charging comprises a plurality of charging operations,
and between subsequent charging operations, disposing a metal plate on a
resin layer formed within the mold to form layers of the resin and the metal
5 plate alternately stacked in the thickness direction.

12. The method for fabricating a printed-wiring substrate according
to claim 9, which comprises roughening at least side surfaces of the capacitor
element before placing the capacitor in the mold.

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13. The method for fabricating a printed-wiring substrate according to claim 10, which comprises roughening at least side surfaces of the capacitor element before placing the capacitor in the mold.

14. The method for fabricating a printed-wiring substrate according to claim 11, which comprises roughening at least side surfaces of the capacitor element before placing the capacitor in the mold.